Box-PC System BPCWL02/03

FANLESS SHUTTLE BOX-PC

WITH INTEL CORE ULV PROCESSOR IN A ROBUST CHASSIS

Shuttle's new generation BPCWL02/03 IPC Series in a ruggedized box design for high durability consists of compact fanless IPC systems with modular expansion for wide-range industrial applications. The model BPCWL03 supports an extended operating temperature range of -20 to +60 °C.

The Shuttle Box-PC series is offered as a complete system: either as a fixed configuration or as an customized BTO system (see page 2). Ask your Shuttle reseller for a quote.

Images for illustration only



Front View (without optional I/O ports)



Rear View



















Robust chassis

2x 32 GB Support

NVMe SSD

Dual LAN (or more)

Serial Port (max. 4)

vPRO/AMT :

75 x 75 mm VESA mount

24/

ROBUST CHASSIS

- Fanless cooling system Robust aluminium/steel chassis
- Dimensions (LWH): $16.9 \times 24.5 \times 5.7 \text{ cm}$ (2.7 L) Net weight: 2.85 kg
- IP Rating: IP30 Mounting options: VESA 75x75 mm, Ear mount 256x100 mm and DIN Rail

OPERATING TEMPERATURE [1]

- Model BPCWL02: 0 +40 °C
- Model BPCWL03: -20 +60 °C
- Operating humidity: 0 ~ 90% (non-condensing)

OPERATING SYSTEM

- An operating system is not included.
- Supports Windows 10/11 and Linux (64-bit)

PROCESSOR SELECTION

Intel Core Gen.	. 8 "Whis	key Lake'	' ULV processoi	r, 15 W TDI	P
CPU Modell	Cores	Threads	Takt / GHz	Cache	AMT/vPro
Core i3-8145UE	2	4	2,2 - 3,9	4 MB	_
Core i5-8365UE	4	8	1,6 - 4,1	6 MB	Supported
Core i7-8665UE	4	8	1,7 - 4,4	8 MB	Supported

GRAPHICS

- Integrated Intel UHD 620 graphics, 4K support
- Optionally supports up to three independent displays

MEMORY SUPPORT

- 2x 260-pin SO-DIMM slot
- Supports Dual Channel, up to 2x 32 GB DDR4-2400

STORAGE

■ M.2-2280/2260 M slot supports one SSD card (supports PCIe X4 NVMe and SATA interface)

BACK PANEL CONNECTORS

- HDMI 1.4 4x USB 3.2 Gen 1 Dual Gigabit LAN (Intel i219LM/i211)
- RS232 serial COM (D-Sub) Mic-in and Line-out (Realtek ALC662 or ALC888S) DC-input 19V (2.5/5.5 mm) Power Button

OTHER FEATURES

- Hardware TPM v2.0 Infineon SLB9670VQ2 onboard
- AMI BIOS, 16/32 MB SPI ROM supports Intel vPro and ATM features
- Embedded I/O controller: ITE IT8528E/FX

OPTIONAL FRONT PANEL CONNECTORS

- Up to two additional graphics ports: HDMI 2.0, DVI-I, DisplayPort 1.2 or D-Sub/VGA
- Up to three additional COM ports
- Up to 8 (16) additional USB 2.0 ports
- Up to four additional 2.5 Gbps LAN ports
- up to four Digital I/O expansion kits (each with 4x Input and 4x Output)
- Input for car ignition lock enables delayed on/off switching of the BoxPC

LTE/WLAN-OPTIONEN

- LTE/4G kit with 2 antennas (LTE card and Nano-SIM not included)
- WLAN kit with 2 antennas either Wi-Fi 5 (ac) or Wi-Fi 6 (ax)

POWER SUPPLY

- DC-Input: 19V, optional wide range DC-input 9~36V
- External 90W/19V power adapter (150W for wide -20...60 °C tempera-

[1] A special 150W power supply is included for the extended operating temperature range (-20 to $+60^{\circ}$ C) and industrial-grade RAM/SSD components with an operating temperature range of -40 ... $+85^{\circ}$ C are required.

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System Configuration

				System	
Vou have the	choice between		Fix C	onf.	BTO
a proposed fi individually as (BTO) system	x configuration and ar ssembled Built-To-Ord		BPCWL02-i3XA Ean: 4046047103652	BPCWL02-i5WA EAN: 4046047103669	Customized Configuration
Category	Choice Options		шш	ш ш	00
Intel ULV Processor	Intel Core i3-8145UE 2 Cores, 4 Threads, 4 MB Ca Intel Core i5-8365UE (vF 4 Cores, 8 Threads, 6 MB Ca Intel Core i7-8665UE (vF	Pro) ache ro)	☑	_ ☑	?
	4 Cores, 8 Threads, 8 MB Ca	ache			
Operation- temperature	BPCWL02: 0 +40 °C Standard power adapter (9) BPCWL03: -20 +60 °C Power Adap. (150W): -20	;	V	Ø	?
Comporatoro	RAM: -40 +85 °C (industr SSD: -40 +85 °C (industri	ial)	_	_	
DC-Input	19V ± 5% (Standard) 936V (Extended Range	2)	<u> </u>	<u></u> ✓	?
	4 GB	,	M	_	
RAM	8 GB		_	$\overline{\mathbf{Z}}$?
DDR4, SO-DIMM	16 GB, 32 GB or 64 GB		_	_	
CCD	120 GB		$\overline{\mathbf{V}}$	_	
SSD M.2 card	250 GB		_	$\overline{\mathbf{V}}$?
141.2 Gal a	512 GB, 1 TB or 2 TB		_	_	
	Without operating syste		☑		
Operating	Windows 10 IoT Enterpris	se	_	\square	
System	Windows 10 Pro (as Windows 11 Downgrade)		_	_	_
(Win10/11 or	Windows 11 Home	1	_	_	?
Linux)	Windows 11 Pro		_	_	
	Linux Ubuntu		_	_	
WLAN Kit	Wi-Fi 5 (WLAN-ac, BT 4.2	.)	_	_	2
with 2 antennas	Wi-Fi 6 (WLAN-ax, BT 5.2)	_	_	?
LTE/4G Kit with 2 antennas	LTE-Kit <u>without</u> M.2 LTE and Nano-SIM card	card	_	_	?
Standard I/O Connectors always included	1x HDMI 1.4 4x USB 3.2 Gen1 2x Gigabit LAN 1x COM (RS232) 2x Audio (mic+head pho	nes)	Ø	V	V
	HDMI 2.0	Ф	_	_	
Optional	DiplayPort (DP 1.2)	One Choice		_	?
Graphics Ports	DVI-I	0 5		_	-
	VGA (second)		V	✓	?
	VGA (second) 4x USB 2.0 (first)		<u> </u>	<u> </u>	?
	4x USB 2.0 (second)		_	_	?
	COM (RS232)		_	_	?
	2x COM (RS232/422/48	5)	7	V	?
Other	4x LAN (RJ45) 2.5 Gbps				?
optional	Dig. I/O (4x Input / 4x Ou		_	_	?
Ports	Input for car ignition lock bles delayed on/off swit of the BoxPC		_	_	?
	Screw terminals for an external power button		_	_	?
Mounting	2x Ear-Mount assembly	olates	_	_	?
Plouriting	DIN-Rail clip		_	–	?



A special 150W power supply is included for the **extended operating temperature range (-20 to +60°C)** and industrial-grade RAM/SSD components with an operating temperature range of -40 ... +85 °C are required.



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LTE Kit

Ear Mount

Ear Mount

Shuttle

LTE Kit

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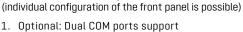
Front and Back Panel

Front panel





Inside View



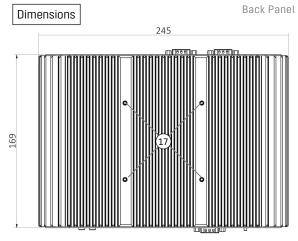
1. Optional: Dual COM ports suppor RS232/RS422/RS485

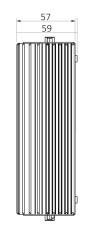
To illustrate with example connections

- 2. Optional: 4x USB 2.0 port
- 3. Optional: HDMI 1.4/2.0
- 4. Audio Line Out (Headphones output)
- 5. Microphone input
- 6. Gigabit LAN port (Intel i211)
- 7. Gigabit LAN port (Intel i219LM)
- 8. 4x USB 3.2 Gen 1 Type A port
- 9. HDMI 1.4 port
- 10. COM port (RS232)
- 11. DC-in connector for power adapter
- 12. Power button
- 13. 2x WLAN antenna (optional)



- 14. Area for optional daughter boards
- 15. 2x SO-DIMM slot supports DDR4-2400
- 16. M.2-2280/2260 M slot for SSD card (NVMe/SATA)
- 17. Screw threads for VESA mount (75x75 mm)





<u>Dimensions:</u>

Width: 245 mm (without optional ear mount)

Depth: 169 mm

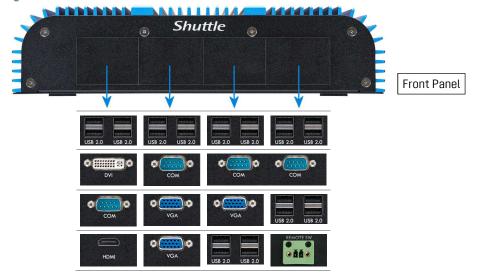
Height: 57 mm (59 mm including feet)



Optional Features

Expansion concept with optional daughter boards

The front panel is subdivided into four sections to support optional expansion kits with daughter boards in order to add I/O ports.



Expansion options:

PORT	IMAGE	OCCUPIED SECTIONS	MAXIMUM KITS	NOTE
HDMI 2.0 DisplayPort 1.2 DVI-I or VGA	HDMI DP DVI	1	1	HDMI 2.0 and DisplayPort 1.2 support UHD resolution (4K) at 60 Hz
Second VGA	○ VGA	1	2	A second VGA port is possible if no HDMI/DP/DVI port has otherwise been installed. The second VGA port is not Plug&Play capable.
4x USB 2.0	USB 2.0 USB 2.0	1	2 (4)	USB hub device (USB 2.0 ports allow up to 500mA/2.5W power output, but if only low power devices like mouse/keyboard are connected, then up to 4 USB kits can be used)
Single COM	COM	1	1	Supports RS232 only (passive cable adapter)
Dual COM	COM COM	2	1	Supports RS232/RS422/RS485 (with additional I/O controller chip)
LTE Kit with 2 antennas	OFF ON SIM1 SIM2	2	1	Compatible with e.g. Huawei ME906S, Sierra EM7455, Quectel EM06E etc. (supports Single-SIM)
1x LAN port 2.5G Upgrade	LAN	_	1	The yellow LAN port (1G) on the back panel can be replaced by a 2.5G LAN port
4x LAN ports with 2.5 Gbps	LAN LAN LAN LAN	2	1	In addition to the existing 2x 1G LAN ports you can add four LAN ports with 2.5G speed
Dig. I/O-Kit 4x ln / 4x Out	DO 4321G	1	4	up to four Digital I/O expansion kits (each with 4x Input and 4x Output)
Input for car ignition lock	5. 5. 2 2 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1	1	1	Input for car ignition lock enables delayed on/off switching of the BoxPC
Port for external Power Button	REMOTE SW	1	1	Screw terminals for a cable for an external power button
WLAN + BT		-	1	1) Wi-Fi 5 (Realtek WLAN-ac and BT 4.2) 2) Wi-Fi 6 (Intel WLAN-ax and BT 5.2)



Operating Positions and Mounting

	NOTE	IMAGE
Placed horizontally	The Shuttle Box-PC BPCWLOx can be operated in horizontal position like a desktop PC standing on its rubber feet.	
VESA-mounted	The Shuttle Box-PC BPCWLOx features four threaded M4 holes on the upper side for a standard 75 x 75 mm VESA mount, which allows for installation on to walls or large displays. The VESA mount is not included.	
Ear-mounted	The Shuttle Box-PC BPCWLOx features four threaded M3 holes on the bottom, which allows for it to be attached to two Ear Mount brackets (optional feature). The Box-PC can then be affixed to a surface with four M4 screws (mounting dimension: 256 mm x 100 mm).	256 mm (100 mm) (100 mm)
DIN-Rail-mounted	The Shuttle Box-PC BPCWLOx features two threaded M3 holes on the bottom, which allows for installation on a standard 35 mm DIN-Rail, e.g. inside equipment racks. The matching DIN-Rail clip is an optional accessory.	47.5 mm



SHUTTLE Box-PC BPCWL02 and BPCWL03 — SPECIFICATIONS

FANLESS AND SILENT	Equipped with passive cooling, no fan noise at all Perfect to be used in noise-sensitive environments Fanless, dust-free and thus virtually maintenance-free
24/7 NONSTOP OPERATION	This device is approved for 24/7 permanent operation. Requirement: Free circulation of air amongst the PC must be guaranteed.
CHASSIS	Durable and rugged chassis made of aluminium and steel. Passive cooling system with specially designed fins to maximize heat dissipation. Dimensions: 16,9 x 24,5 x 5,7 cm (LWH) = approx. 2,7 litres Weight: 2.85 kg net (Barebone without RAM/SSD and optional expansions) IP-rating: IP30
OPERATING POSITIONS AND MOUNTING	1) The unit can be placed horizontally to stand on its feet. 2) The unit can be affixed to a 75 mm x 75 mm VESA bracket. For this purpose, four M4x6L screws are required to be screwed into the chassis from the top. 3) The unit can be mounted using two optional 256 mm x 100 mm ear-mount brackets. For this purpose, four M3x6L screws are required to be screwed into the chassis from the bottom. 4) Mounted on a standard 35 mm DIN-Rail, e.g. inside equipment racks Notes: VESA bracket, Ear-Mount and DIN-Rail clip are not included. Vertical mounting is permitted in any orientation.
OPERATING SYSTEM	This system is compatible with Windows 10/11 (64-bit) and Linux (64-bit).
PROCESSOR	Available Processors Threads Cache Clock frequency VPro Support Intel UHD Graphics Intel Core i3-8145UE 2 / 4 4 MB 2.2-3.9 GHz - UHD 620, 300-1000 MHz Intel Core i5-8365UE 4 / 8 6 MB 1.6-4.1 GHz Yes UHD 620, 300-1050 MHz Intel Core i7-8665UE 4 / 8 8 MB 1.7-4.4 GHz Yes UHD 620, 300-1150 MHz System-on-a-chip architecture (SoC) with integrated memory and graphics controller FCBGA1528 package - directly soldered onto the mainboard Code name: Whiskey Lake-U (8th Generation Intel Core), Manufacturing process: 3rd-generation enhanced 14nm++ TDP wattage: 15 W maximum
INTEGRATED GRAPHICS	Intel UHD Graphics 620 GPU clock frequency: 300~1050 MHz Execution Units (EUs): 24 Supports up to three independent screens: 1) HDMI 1.4 on the backpanel 2) optional HDMI 1.4/2.0, DisplayPort 1.2, DVI-I or D-Sub/VGA (DDI interface) 3) optional D-Sub/VGA (eDP interface, limitations: no PnP support)
UEFI BIOS	Supports resume after power failure Supports Wake on LAN (WOL) Supports Power on by RTC Alarm Supports boot from M.2 SSD cards and USB devices AMI BIOS in 16 or 32 MB EEPROM with SPI interface Supports hardware monitoring and Watchdog function Supports Unified Extensible Firmware Interface (UEFI)
INTEL vPRO/AMT	Supports Intel® vPro™ and AMT – only in connection with Intel Core i5-8365UE or Intel Core i7-8665UE processors Intel® vPro™ is a brand name for a specific set of management and security technologies. Intel® Active Management Technology (AMT) is a subset of Intel vPro. This technology allows remote management of PCs, even in power-off mode or with non-functional operating systems. You can audit, repair and restore AMT-based platforms in a LAN. These functions can increase the uptime of desktops with lower maintenance costs. Note: Intel vPro requires appropriate software. The Intel® MEBX configuration user interface can be accessed after pressing CTRL-P at the beginning of the boot process. Only the Intel i219 LAN port (yellow color) supports the Intel vPro® function.
TPM MODULE	Hardware Trusted Platform Module (Infineon SLB9670VQ2 TPM 2.0)



PRODUCT SPECIFICATIONS

	Box-PC	Operating Temperature	Output Wattage	AC Input	DC Output	AC Cable
	BPCWL02	0 to +40°C	Max. 90 W	100-240V, 50/60Hz	19V, max. 4.74A	Schuko to IEC 60320 C5
POWER ADAPTER [1]	BPCWL03	-20 to +60°C	Max. 150 W (95W at 60°C)	90-260V, 50/60Hz	19V, max. 7.89A	Schuko to IEC 60320 C13
	AC mains cab and CEE-7/7 p	lug with earth-conta	ength, with C5/C6 act (type E+F) for t			er-leaf") for the power adapter
MEMORY SUPPORT [1]	Supports DDR Supports Dua Supports a ma maximum tot	lot with 260 pins 4-2400 (PC4-19200 I Channel mode aximum of 32 GB per al size: 64 GB unbuffered DIMM m	DIMM,	egistered)		
M.2 SLOT For SSDs [1]	- PCI-Express - SATA v3.0 (It supports M and a length	max. 6 Gbps) 1.2 cards with a wi of 60 or 80 mm (t	dth of 22 mm ype 2260, 2280).		th M key) with a	uto detect
AUDIO	Two analog at 1) 2 channel li 2) microphone	® ALC662 or ALC88 udio connectors (3.5 ne out (headphones e input shannel audio output	mm) on the back p	oanel:		
DUAL GIGABIT LAN	Used network 1) Intel i211 Et 2) Intel i219LN Supports 10 / Supports WAN	hernet Controller wi 4 PHY connected to 100 / 1000 MBit/s o (E ON LAN (WOL) work boot by Preboo	th MAC, PHY and P the MAC of the pro operation	cessor		
BACK PANEL CONNECTORS	2x Intel Gigab Serial COM po Microphone in Audio Line-ou	en 1 Type A (max. 5 G it LAN (RJ45, i211/i2 rt (RS232)	19LM) [3] mm)			
DPTIONAL FRONT Panel Connectors	ports. The foll 1) second grap 2) third graph 3) one COM po 4) two COM po 5) 4x USB 2.0 devices like m 6) 2x or 4x LA 7) up to four E 8) Input for ca 9) LTE kit with Quectel EMO6	owing accessory kit obics port: HDMI 2.0 ics port: D-Sub/VGA ort RS232 orts RS232/RS422/- can be installed two use/keyboard are N ports with 2.5 Gbp ligital I/O expansion ar ignition lock enabl	s can be pre-instal DisplayPort 1.2 or RS485 (occupies trice (Note: USB 2.0 connected, then ups transfer speed kits (each with 4x es delayed on/off snas. Not included: rd.	led by Shuttle upon red D-Sub/VGA wo sections) ports allow up to 500r o to 4 USB kits can be u Input and 4x Output) [2 switching of the BoxPC LTE card in M.2-3042 f	nuest for an addition mA/2.5W power of sed)	nter boards in order to add I/O onal charge: utput, but if only low power ei ME906S, Sierra EM7455,
FURTHER OPTIONAL ACCESSORIES	2) Ear-mount 3) DIN-Rail cli	DC-input 9~36 V (in brackets (mounting o (holes without thre ule with two externa	dimensions: 256 n ead)		BT 4.2) or Wi-Fi 6	(WLAN-ax and BT 5.2)



PRODUCT SPECIFICATIONS

	Box-PC	Operating temperature	Relative humidity
ENVIRONMENTAL	BPCWL02	0 to +40°C	0-90 %, non-condensing
SPECIFICATIONS	BPCWL03	-20 to +60°C	0-90 %, non-condensing
	Notice the foot	tnote [1]	
		lass A, VCCI, RCM, BSMI	
	Safety: CB, cTl	·	
	Other: RoHS, E	,	
CONFORMITY AND			formation equipment (ITE) i
CERTIFICATIONS		• • • • • • • • • • • • • • • • • • • •	the conformity by the EU
	(1) 2014/30/El	J relating to electromagi	netic compatibility (EMC),
	(2) 2014/35/EI	U relating to Electrical Ed	quipment designed for use
	(3) 2009/125/	EC relating to eco design	requirements for energy-i

[1] A special 150W power supply is included for the **extended operating temperature range (-20 to +60°C)** and industrial-grade RAM/SSD components with an operating temperature range of -40 ... +85 °C are required.
[2] **The DIO expansion kit** comes with the appropriate plug connector included. The digital inputs recognize "Low" at 0-3 Volt and "High" at 5-30 Volt (or open). The digital outputs can handle 0-30V (open collector) with up to 30 mA current.